

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	(mask and substrate and (mating or mated)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/29 16:04
L2	57	(mask and substrate and (contacting)).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/29 16:04
L3	23	((depositing or forming) and mask\$3).clm. and ((multilayer or multi-layer) near2 (three-dimensional)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/29 16:06
S1	232	((cohen near2 adam) (dennis near2 smalley)).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:06
S3	36	((cohen near2 adam) (dennis near2 smalley)).in. and (depositing and mask\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:55
S4	978	(216/2).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/26 13:20
S6	44	(216/43).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:50
S7	14279	(depositing or forming).clm. and (multilayer or multi-layer) near2 (mems or micromechanical or microstructure\$1 or microelectromechanical or structure)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 17:20
S8	2419	(depositing or forming).clm. and ((multilayer or multi-layer) near2 (mems or micromechanical or microstructure\$1 or microelectromechanical or structure)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/26 13:38

## EAST Search History

S9	868	(depositing or forming and mask\$3). clm. and ((multilayer or multi-layer) near2 (mems or micromechanical or microstructure\$1 or microelectromechanical or structure)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/26 13:38
S10	411	((depositing or forming) and mask\$3). clm. and ((multilayer or multi-layer) near2 (mems or micromechanical or microstructure\$1 or microelectromechanical or structure)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/29 16:06
S11	4	("5493096") or ("6183064").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/27 20:05
S12	322	(depositing or forming).clm. and (mask\$3 near5 curvature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:02
S13	330	(depositing or forming).clm. and (contact adj mask\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:02
S14	346	(depositing or forming or etching).clm. and (contact adj mask\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:02
S15	6	(depositing or forming or etching).clm. and (contact adj mask\$3).clm. and curvature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:03
S16	6	(depositing or forming or etching).clm. and (contact adj mask\$3).clm. and (curvature or convex or concave or curved).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:05
S17	208	(118/721).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:17

## EAST Search History

S18	34	S17 and (curvature or convex or concave or curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:08
S19	361	flexible adj mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 13:55
S20	1459	deposition adj mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:25
S21	157	(deposition adj mask).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:28
S22	3	(mask and substrate and mating).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/29 16:02
S23	4	(mask\$1 and substrate\$1 and mating).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/09 17:30
S24	724	contact adj mask and (curvature or convex or concave or curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 15:53
S25	267	deposition adj mask and (curvature or convex or concave or curved)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:24
S26	1397	(216/41).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:32
S27	46	(216/43).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:25

## EAST Search History

S28	34	(216/45).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:25
S29	43	(156/345.19).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:32
S30	101	(156/345.3).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:32
S31	74	(smalley and cohen).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/11 13:52
S32	34	156/dig.19.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 15:53
S33	81	156/dig.20.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 15:53
S34	774	((contact or deposition) adj2 mask) and (electrochemical or electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:48
S35	116	((contact or deposition) adj2 mask) and (electrochemical or electrodeposit\$4).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:01
S36	168	((contact or deposition) adj2 mask) and (electrochemical or electrodeposit\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:11
S37	2	("6027630").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:38

## EAST Search History

S38	136	(instant adj mask\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:38
S39	34	(216/45).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:50
S40	5	((cohen near2 adam) (dennis near2 smalley)).in. and ((mating or mated) and mask\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:56
S41	483	((mating or mated) and mask\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 16:57
S42	246	((mating or mated) and mask\$3).clm. and (electrochemical or deposit\$4 or etching)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 17:11
S43	1	("4388388").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/27 17:10
S44	100	(pre-patterned near2 mask\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 16:37
S45	240	(205/666).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 17:58
S46	306	(205/206).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/27 17:58
S47	2	("6027630").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:06

## EAST Search History

S48	303	(205/135).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:38
S49	7	((pressed or pressing) adj2 mask).clm. and (electroless or plating or electrochemical or electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:49
S50	19	((pressed or pressing) near3 mask).clm. and (electroless or plating or electrochemical or electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:51
S51	20	((pressed or press-fit\$3 or pressing) near3 mask).clm. and (electroless or electrolytic or plating or electrochemical or electrodeposit\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:02
S52	240	(205/666).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 12:59
S53	82	(205/667).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:00
S55	108	((pressed or press-fit\$3 or pressing) near3 mask) and (electroless or electrolytic or plating or electrochemical or electrodeposit\$4). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:02
S56	2	((pressed or press-fit\$3 or pressing) near3 mask) with bath and (electroless or electrolytic or plating or electrochemical or electrodeposit\$4). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:02
S57	3	((pressed or press-fit\$3 or pressing) near3 mask) with bath	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:03
S58	7	((pressed or press-fit\$3 or pressing) near3 mask) with (bath or electrolyte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/28 13:03

## EAST Search History

S59	345	((contact or adhesive) adj mask) and electrochemical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 15:57
S60	64	((contact or adhesive) adj mask) and electrochemical and (bubbles or (air adj pockets))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 15:54
S61	1427	(216/41).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 15:59
S62	152	((etching or plating) near2 mask\$3).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 16:59
S63	284	(118/406).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 16:41
S64	0	((electrochemical or electrolytic) near2 mask\$3).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:16
S65	0	((electrochemical or electrolytic) near3 mask\$3).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 16:59
S66	32	((electrochemical or electrolytic) near3 mask\$3).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:00
S67	55	((cohen near2 adam) (dennis near2 smalley)).in. and depositing.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 17:05
S68	137	((electrochemical or electrolytic) and (micromechanical or microelectromechanical or microstructure\$1 or MEMS or multilayer)).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:08
S69	57	((electrochemical or electrolytic) and (micromechanical or microelectromechanical or microstructure\$1 or MEMS)).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:08

## EAST Search History

S70	36	((mating or mated) and mask\$3).clm. and (electrochemical or electrolytic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 17:15
S71	8	((electroplating) near2 mask\$3).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:17
S72	26	((adhesive) near2 mask\$3).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:19
S73	63	((adhesive) near3 mask\$3) with (plating or electroplating)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:23
S74	12	((soft) near3 mask\$3) with (plating or electroplating)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:28
S75	8692	mask\$3 with (plating or electroplating)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:29
S76	529	(mask\$3 with (plating or electroplating)).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:29
S77	55	(mask\$3 with (plating or electroplating)).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/14 17:35
S78	13	("4126521") or ("3527679") or ("4294681").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/14 17:35
S79	14	(flexible adj2 mask) with (etching or plating or electroplat\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 16:05
S80	124	(flexible adj2 mask) and (etching or plating or electroplat\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 15:38
S81	59	(flexible adj2 mask) with (fluid or pressure or vacuum)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 16:08
S82	18	(flexible adj2 mask) with (adhesive)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 16:08
S83	385	(flatten with vacuum)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:19

## EAST Search History

S84	12	(flatten with vacuum) and (holder or chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:16
S85	57	(flatten with vacuum) and mask	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:19
S86	171	(flatten\$3 with vacuum) and mask	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:32
S87	11	(flatten\$3 with vacuum) with mask	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:19
S88	406	flatten\$3 near3 mask	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:39
S89	135	(curvature near3 mask).clm.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:44
S90	148	(\$7plating near3 mask).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/18 16:45
S91	606	(\$7plating near3 mask).ab.	JPO	OR	OFF	2006/07/18 16:46
S92	1084	(\$7plating near3 mask).ab.	JPO; DERWENT	OR	OFF	2006/07/18 16:45
S93	6	(\$7plating and curvature and mask).ab.	JPO	OR	OFF	2006/07/18 17:22
S94	2	("4388388").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/18 17:22
S95	1889	(156/285).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 10:58
S96	428	(156/87).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 10:57
S98	100	S95 and mask\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 10:58

## EAST Search History

S99	105	S95 and (mask\$3 or stencil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:29
S100	46	S95 and S96	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 11:14
S101	1	("4127436").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/19 11:16
S102	76	((plating or electroplating) and curved).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:29
S103	428	(156/87).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:54
S104	3	(("7073223") or ("20050182372")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/19 14:55
S105	7	(("6564030") or ("5670202") or ("6136141")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/21 15:12
S108	198	(cc or conformable) adj mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/24 13:55